

1. General description

WG30N65MF1 uses advanced Fine Trench Field-stop IGBT technology with anti-parallel diode in TO-220AB package to provide extremely low $V_{ce(sat)}$, and excellent switching performance. This device offers Best-in-Class efficiency in hard switching and resonant topology.



2. Features and benefits

- Maximum junction temperature 175 °C
- Positive Temperature efficient for easy paralleling
- Very soft, fast recovery anti-parallel diode
- Smooth & Optimized switching
- EMI Improved Design

3. Applications

- PFC
- Solar converters
- UPS
- Welding Converters
- Mid to high range switching frequency converters

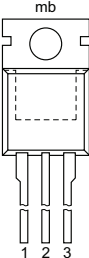
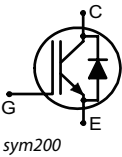
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Notes	Value			Unit	
V _{CE}	Collector-emitter voltage, T _j ≥ 25 °C		650			V	
I _C	DC collector current, limited by T _{j(max)} T _C = 100 °C		30			A	
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V _{CE(sat)}	Collector-emitter saturation voltage	V _{GE} = 15 V; I _C = 30 A; T _j = 25 °C		-	1.6	2.1	V

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		 <i>sym200</i>
2	C	collector		
3	E	emitter		
mb	C	mounting base; connected to collector		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WG30N65MF1	TO220AB	WG30N65MF1Q	Tube	50	SOT78	13-Jun-2008

7. Marking

Table 4. Marking codes

Type number	Marking codes
WG30N65MF1	WG30N 65MF1

8. Limiting values

Table 5. Limiting values

Symbol	Parameter	Notes	Value	Unit
V_{CE}	Collector-emitter voltage, $T_j \geq 25\text{ °C}$		650	V
I_C	DC collector current, limited by $T_{j(max)}$ $T_C = 25\text{ °C}$ $T_C = 100\text{ °C}$		60 30	A
$I_{C(puls)}$	Pulsed collector current, t_p limited by $T_{j(max)}$		90	A
-	Turn off safe operating area $V_{CE} \leq 650\text{ V}$, $T_j \leq 175\text{ °C}$, $t_p = 1\text{ }\mu\text{s}$		90	A
I_F	Diode forward current, limited by $T_{j(max)}$ $T_C = 25\text{ °C}$ $T_C = 100\text{ °C}$		60 30	A
I_{Fpuls}	Diode pulsed current, t_p limited by $T_{j(max)}$		90	A
V_{GE}	Gate-emitter voltage		± 20	V
P_{tot}	Power dissipation $T_C = 25\text{ °C}$ Power dissipation $T_C = 100\text{ °C}$		312 156	W
t_{sc}	Short circuit withstand time $V_{GE} = 15.0\text{ V}$, $V_{CC} \leq 400\text{ V}$ Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0\text{ s}$ $T_j = 175\text{ °C}$		5	us
T_{stg}	Storage temperature		-55 to +150	°C
T_{jmax}	Maximum operating junction temperature		175	°C
-	Peak soldering temperature		260	°C
M	Mounting Torque with washer		0.55	Nm

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-c)}$	IGBT thermal resistance from junction to case			-	0.48	-	K/W
$R_{th(j-c)}$	Diode thermal resistance from junction to case			-	0.94	-	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient			-	40	-	K/W

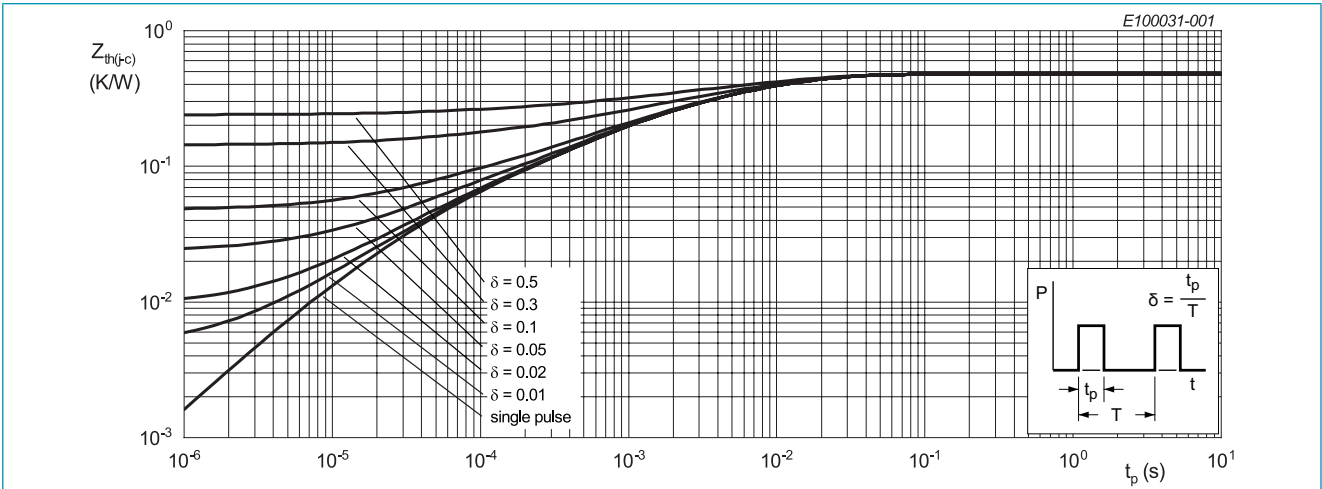


Fig. 1. Transient thermal impedance from junction to case as a function of pulse duration; IGBT

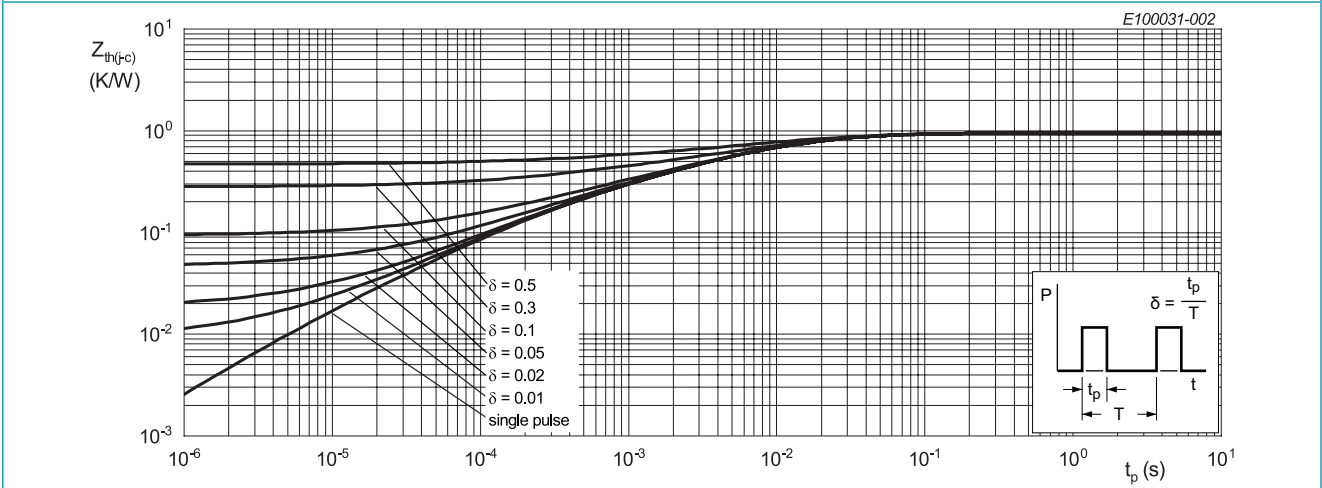


Fig. 2. Transient thermal impedance from junction to case as a function of pulse duration; Diode

10. Characteristics

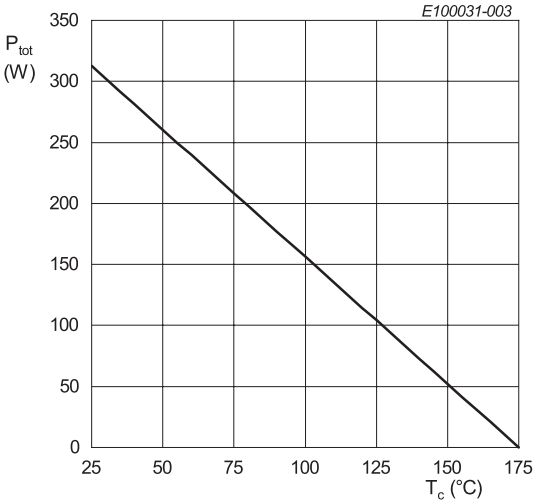
Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
BV_{CES}	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}; I_C = 1.0\text{ mA}$		650	-	-	V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}; I_C = 30\text{ A}; T_j = 25\text{ }^{\circ}\text{C}$		-	1.6	2.1	V
		$V_{GE} = 15\text{ V}; I_C = 30\text{ A}; T_j = 175\text{ }^{\circ}\text{C}$		-	2.1	-	V
V_F	Diode forward voltage	$V_{GE} = 0\text{ V}; I_F = 30\text{ A}; T_j = 25\text{ }^{\circ}\text{C}$		-	1.9	-	V
		$V_{GE} = 0\text{ V}; I_F = 30\text{ A}; T_j = 175\text{ }^{\circ}\text{C}$		-	1.5	-	V
$V_{GE(th)}$	Gate-emitter threshold voltage	$I_C = 0.6\text{ mA}; V_{CE} = V_{GE}$		4.3	5.5	6.6	V
I_{CES}	Zero gate voltage collector current	$V_{CE} = 650\text{ V}; V_{GE} = 0\text{ V}; T_j = 25\text{ }^{\circ}\text{C}$		-	-	100	μA
		$V_{CE} = 650\text{ V}; V_{GE} = 0\text{ V}; T_j = 175\text{ }^{\circ}\text{C}$		-	-	1	mA
g_{fs}	Transconductance	$V_{CE} = 20\text{ V}; I_C = 30\text{ A}$		-	13	-	S
Dynamic characteristics							
C_{ies}	Input capacitance	$V_{CE} = 30\text{ V}; V_{GE} = 0\text{ V}; f = 1\text{ MHz}; T_j = 25\text{ }^{\circ}\text{C}$		-	1626	-	pF
C_{oes}	Output capacitance			-	84	-	pF
C_{res}	Reverse transfer capacitance			-	17	-	pF
Q_G	Gate charge	$V_{CC} = 520\text{ V}; I_C = 30\text{ A}; V_{GE} = 15\text{ V}; T_j = 25\text{ }^{\circ}\text{C}$		-	70	-	nC

11. Switching Characteristics

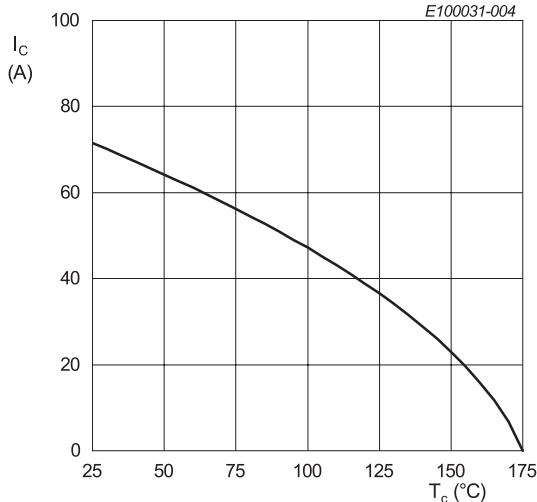
Table 8. Switching Characteristics, Inductive Load

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
IGBT characteristics							
t _{d(on)}	Turn-on delay time	T _J = 25 °C; V _{CC} = 400 V; I _C = 30 A; V _{GE} = 15V / 0V; R _G = 10 Ω		-	32	-	nS
t _r	Rise time			-	39	-	nS
t _{d(off)}	Turn-off delay time			-	119	-	nS
t _f	Fall time			-	38	-	nS
E _{on}	Turn-on energy			-	0.7	-	mJ
E _{off}	Turn-off energy			-	0.38	-	mJ
E _{ts}	Total switching energy			-	1.08	-	mJ
t _{d(on)}	Turn-on delay time	T _J = 175 °C; V _{CC} = 400 V; I _C = 30 A; V _{GE} = 15V / 0V; R _G = 10 Ω		-	32	-	nS
t _r	Rise time			-	40	-	nS
t _{d(off)}	Turn-off delay time			-	137	-	nS
t _f	Fall time			-	71	-	nS
E _{on}	Turn-on energy			-	1.3	-	mJ
E _{off}	Turn-off energy			-	0.6	-	mJ
E _{ts}	Total switching energy			-	1.9	-	mJ
Diode characteristics							
t _{rr}	Reverse recovery time	T _J = 25 °C; V _R = 400 V; I _F = 30 A; dI _F /dt = 500A/us		-	44	-	nS
Q _r	Reverse recovery charge			-	221	-	nC
I _{RM}	Reverse recovery peak current			-	9	-	A
t _{rr}	Reverse recovery time	T _J = 175 °C; V _R = 400 V; I _F = 30 A; dI _F /dt = 500A/us		-	100	-	nS
Q _r	Reverse recovery charge			-	990	-	nC
I _{RM}	Reverse recovery peak current			-	17	-	A



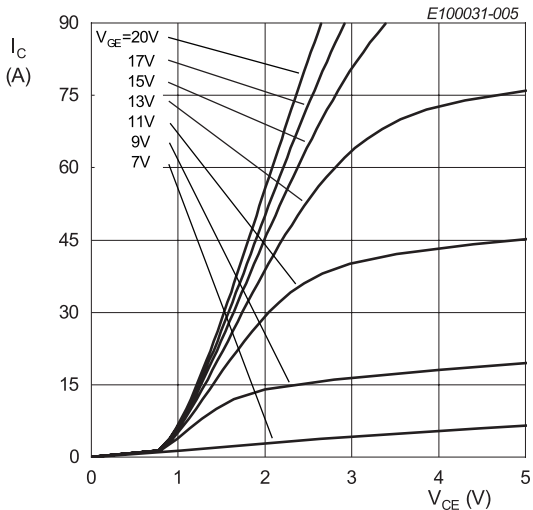
$T_j \leq 175\text{ °C}$

Fig. 3. Power dissipation as a function of case temperature



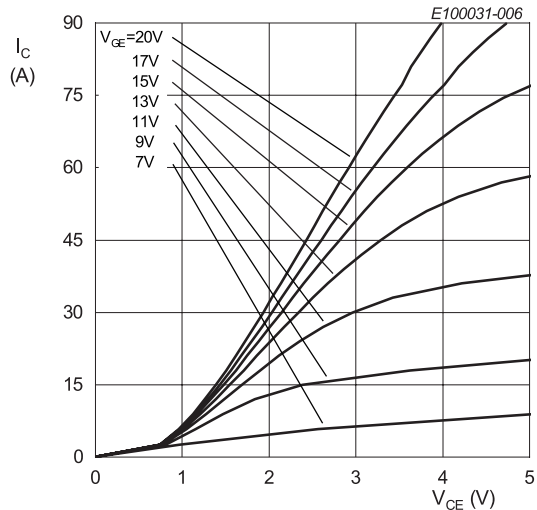
$V_{GE} \geq 15\text{ V}; T_j \leq 175\text{ °C}$

Fig. 4. Collector current as a function of case temperature



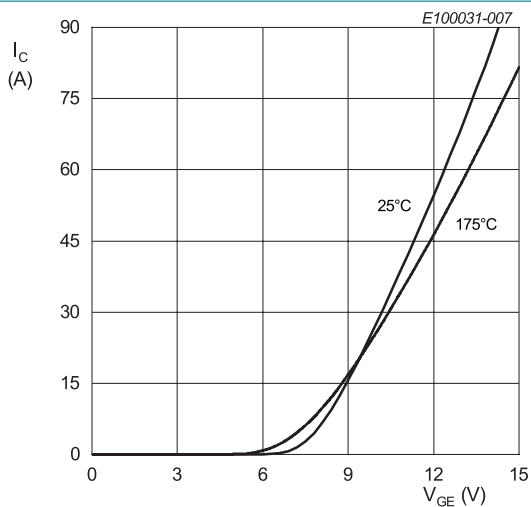
$T_j = 25\text{ °C}$

Fig. 5. Typical output characteristic



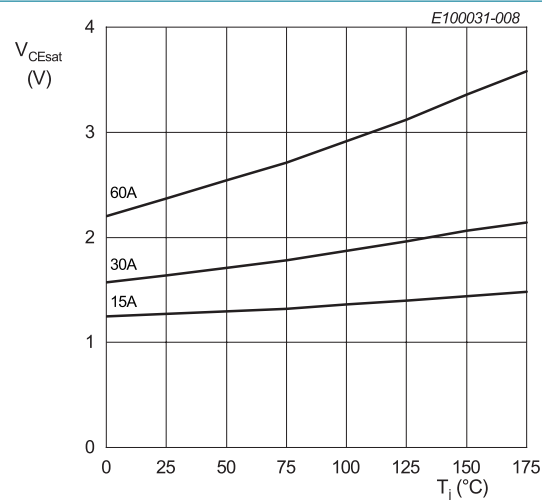
$T_j = 175\text{ °C}$

Fig. 6. Typical output characteristic



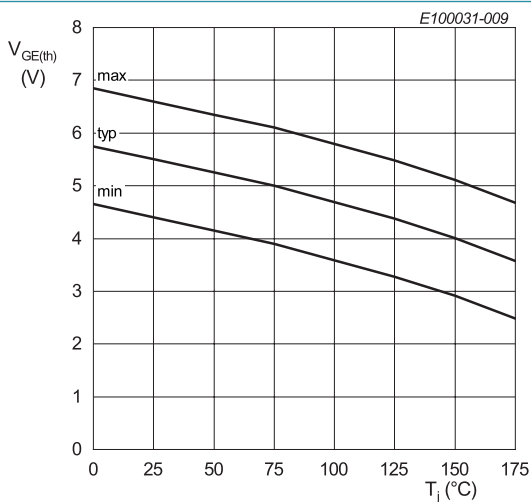
$V_{CE} = 20V$

Fig. 7. Typical transfer characteristic



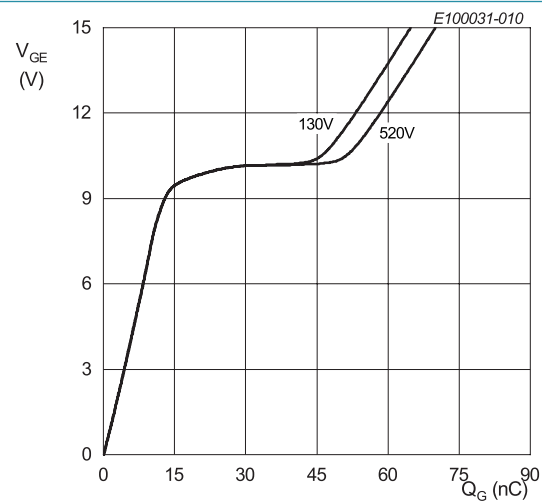
$V_{GE} = 15V$

Fig. 8. Typical collector-emitter saturation voltage as a function of junction temperature



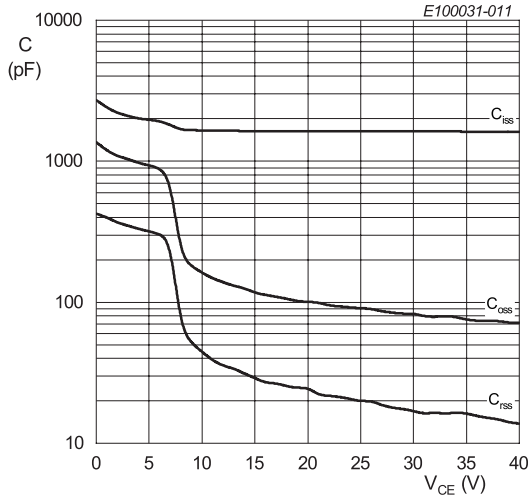
$I_C = 600\mu A$

Fig. 9. Gate-emitter threshold voltage as a function of junction temperature



$I_C = 30A$

Fig. 10. Typical gate charge



$V_{GE} = 0 \text{ V}$; $f = 1 \text{ MHz}$

Fig. 11. Typical capacitance as a function of collector-emitter voltage

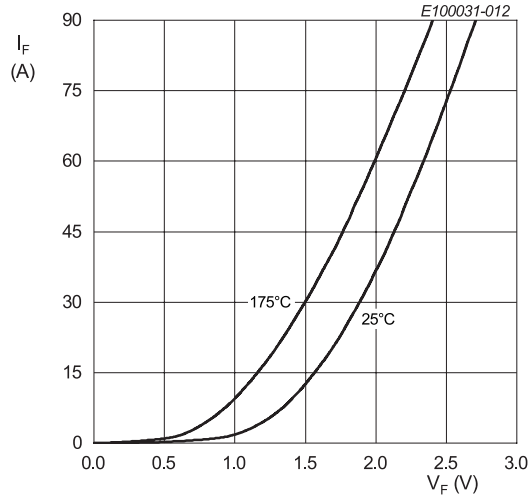
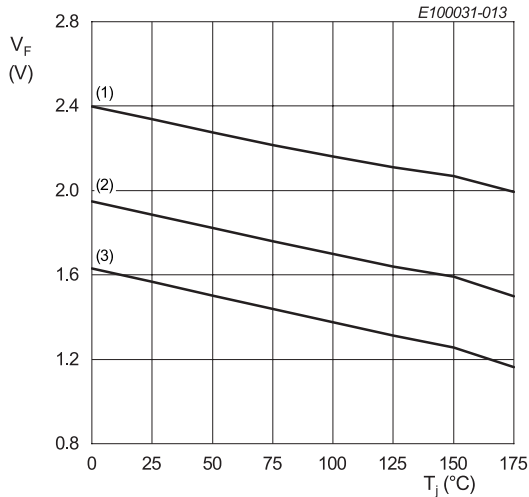
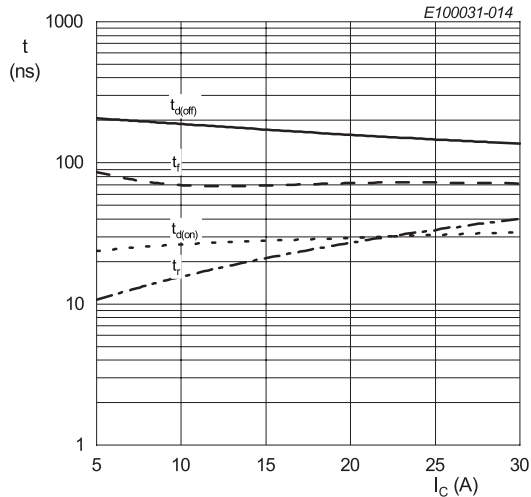


Fig. 12. Typical diode forward current as a function of forward voltage



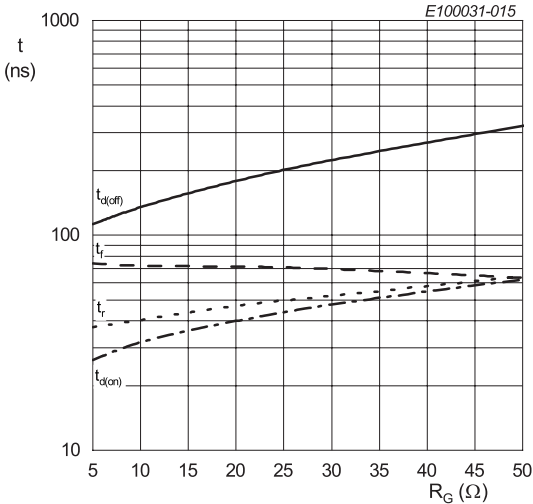
- (1) $I_F = 60 \text{ A}$
- (2) $I_F = 30 \text{ A}$
- (3) $I_F = 15 \text{ A}$

Fig. 13. Typical diode forward voltage as a function of junction temperature



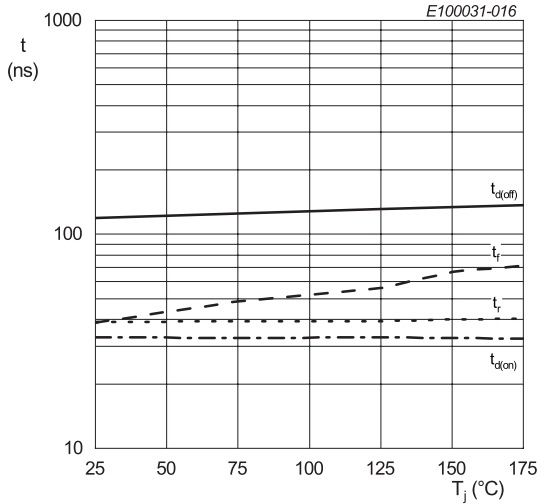
$R_g = 10 \text{ } \Omega$; $V_{GE} = 15\text{V}/0\text{V}$; $T_J = 175 \text{ } ^\circ\text{C}$;
 $V_{CE} = 400 \text{ V}$; inductive load

Fig. 14. Typical switching times as a function of collector current



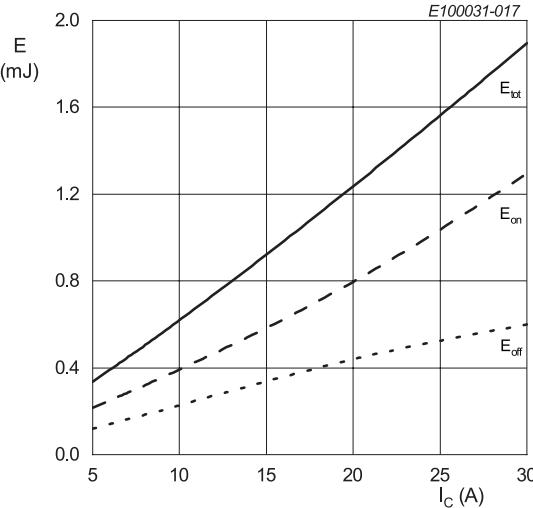
I_C = 30 A; V_{GE} = 15V/0V; T_J = 175 °C;
V_{CE} = 400 V; inductive load

Fig. 15. Typical switching times as a function of gate resistance



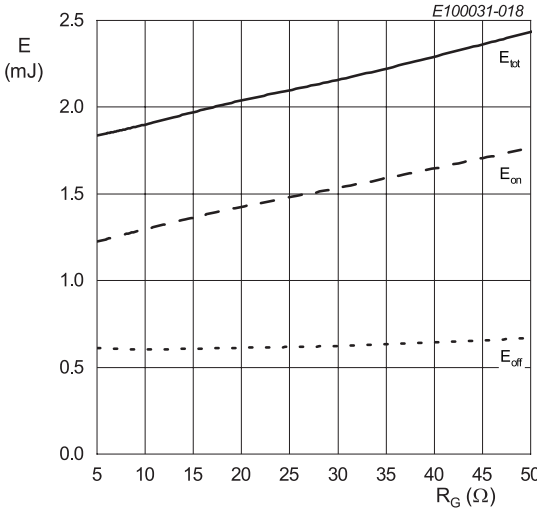
I_C = 30 A; V_{GE} = 15V/0V; R_g = 10 Ω;
V_{CE} = 400 V; inductive load

Fig. 16. Typical switching times as a function of junction temperature



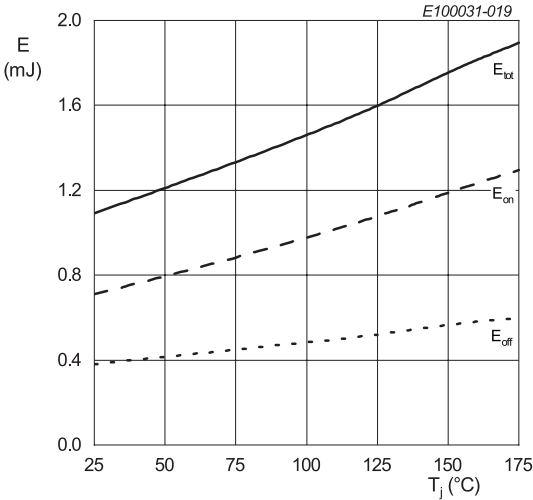
R_g = 10 Ω; V_{GE} = 15V/0V; T_J = 175 °C;
V_{CE} = 400 V; inductive load

Fig. 17. Typical switching energy losses as a function of collector current



I_C = 30 A; V_{GE} = 15V/0V; T_J = 175 °C;
V_{CE} = 400 V; inductive load

Fig. 18. Typical switching energy losses as a function of gate resistance



$I_C = 30\text{ A}$; $V_{GE} = 15\text{ V}/0\text{ V}$; $R_g = 10\ \Omega$;
 $V_{CE} = 400\text{ V}$; inductive load

Fig. 19. Typical switching energy losses as a function of junction temperature

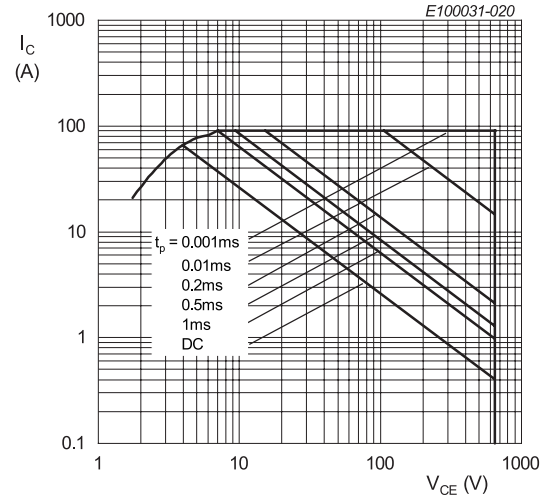


Fig. 20. Forward bias safe operating area

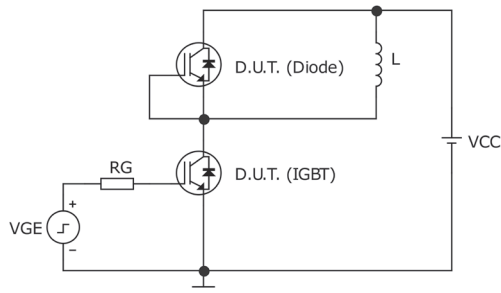


Fig. 21. Test circuit for inductive load switching

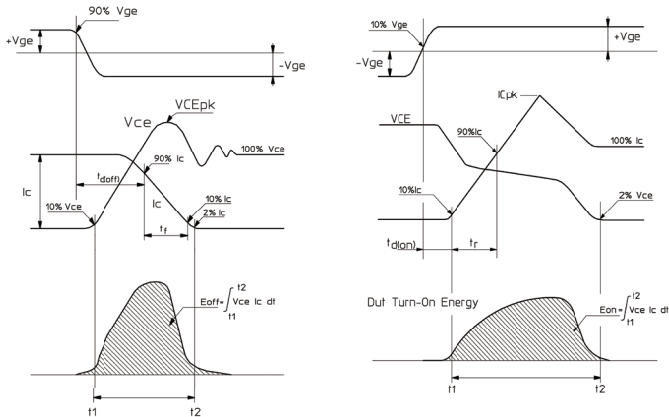
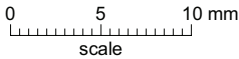
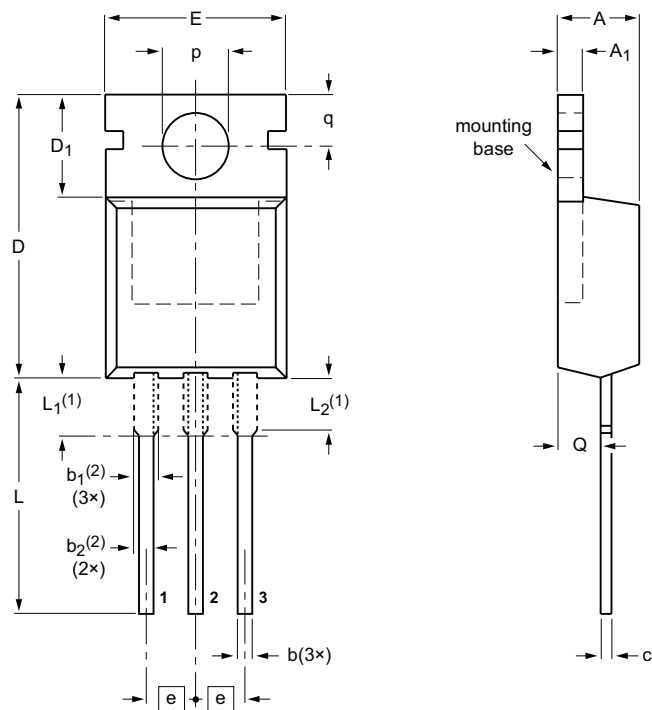


Fig. 22. Definition of switching times and losses

12. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	b ₁ (2)	b ₂ (2)	c	D	D ₁	E	e	L	L ₁ (1)	L ₂ (1) max.	p	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

- Notes
- 1. Lead shoulder designs may vary.
 - 2. Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT78		3-lead TO-220AB	SC-46			08-04-23 08-06-13

13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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